

Doc. Number :

- ☐ Tentative Specification
☒ Preliminary Specification
☐ Approval Specification

MODEL NO.: M236HJJ
 SUFFIX: L31

Customer:

APPROVED BY

SIGNATURE

Name / Title

Note

Product Version C1

Please return 1 copy for your confirmation with your signature and comments.

Approved By	Checked By	Prepared By
		向芝芬

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REVISION HISTORY

Version	Date	Page	Description
1.0	Jun./2014	1	SUFFIX:L30 change to L31
		5	1.2 Surface Treatment / Power Consumption
			2. MECHANICAL SPECIFICATIONS(tolerance change)
		9	4.3.1 Power Supply Current/ Power Consumption
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1. GENERAL DESCRIPTION

1.1 OVERVIEW

M236HJJ-L31 is a 23.6" TFT Liquid Crystal Display module white-LED back-light unit and 30 pins 2 channels LVDS interface. This module supports 1920x1080 native resolutions and can display up to 16.7 millions colors. The converter module for Backlight is not built in.

1.2 GENERAL SPECIFICATIONS

Item	Specification	Unit	Note
Active Area Size	23.6" real diagonal		
Driver Element	a-si TFT active matrix	-	
Pixel Number	1920 x R.G.B. x 1080	pixel	
Pixel Pitch	0.2715(H) x 0.2715(V)	mm	
Pixel Arrangement	RGB vertical stripe	-	
Display Colors	16.7M	color	
Transmissive Mode	Normally black	-	
Luminance, White	250	cd/m ²	
Color Gamut	72% of NTSC(Typ.)	-	
TCO	TCO 6.0	-	
Surface Treatment	AG type, 3H hard coating, Haze :25%		
Power Consumption	Total(TBD)W@ cell (TBD)W, BL(13.3) (W)		(1)

Note (1) The specified power consumption: Total= cell(reference 4.3.1)+BL(reference 4.3.3)

2. MECHANICAL SPECIFICATIONS

Item		Min.	Typ.	Max.	Unit	Note
Module Size	Horizontal	544.3	544.8	545.3	mm	(1)
	Vertical	320	320.5	321	mm	
	Thickness	10.5	11	11.5	mm	
Bezel Area	Horizontal	524.92	525.22	525.52	mm	
	Vertical	296.92	297.22	297.52	mm	
Active Area	Horizontal	-	521.28	-		
	Vertical	-	293.22	-	mm	
Weight		2195	2305	2415		

Note (1) Please refer to the attached drawings for more information of front and back outline dimensions.

3. ABSOLUTE MAXIMUM RATINGS

3.1 ABSOLUTE RATINGS OF ENVIRONMENT

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Storage Temperature	TST	-20	60	°C	(1)
Operating Ambient Temperature	TOP	0	50	°C	(1), (2)

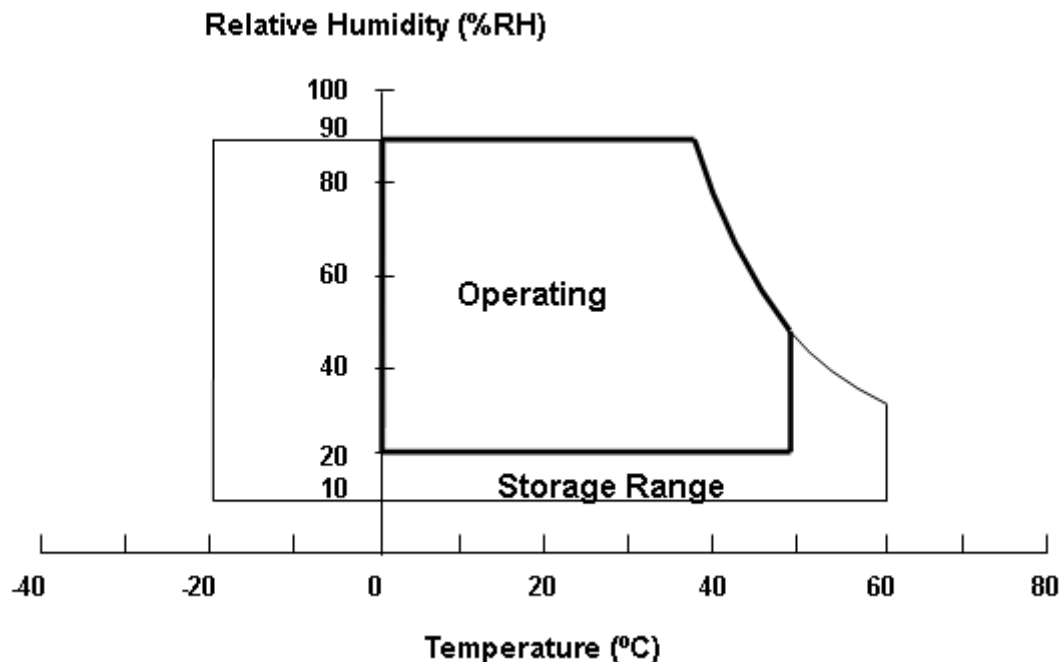
Note (1)

(a) 90 %RH Max. (Ta < 40 °C).

(b) Wet-bulb temperature should be Ta < 40 °C

(c) No condensation.

Note (2) Panel surface temperature should be 0°C min. and 65°C max under Vcc=5.0V, fr =60Hz, typical LED string current, 25°C ambient temperature, and no humidity control . Any condition of ambient operating temperature ,the surface of active area should be keeping not higher than 65°C.



3.2 ELECTRICAL ABSOLUTE RATINGS

3.2.1 TFT-LCD MODULE

Item	Symbol	Value		Unit	Note
		Min.	Max.		
Power Supply Voltage	VCCS	-0.3	6.0	V	(1)
Logic Input Voltage	V _{IN}	-0.3	3.6	V	

3.2.2 BACKLIGHT UNIT

Item	Symbol	Value			Unit	Note
		Min.	Typ	Max.		
LED Forward Current Per Input Pin	I _F	---	95	110	mA	(1), (2) Duty=100%
LED Pulse Forward Current Per Input Pin	I _P	---	---	150	mA	(1), (2) Pulse Width ≤ 10msec. and Duty ≤ 30%

Note (1) Permanent damage to the device may occur if maximum values are exceeded. Function operation should be restricted to the conditions described under Normal Operating Conditions.

Note (2) Specified values are for input pin of LED light bar at Ta=25±2 °C (Refer to 4.3.3 and 4.3.4 for further information).

4. ELECTRICAL SPECIFICATIONS4.1 FUNCTION BLOCK DIAGRAM

4.1 FUNCTION BLOCK DIAGRAM

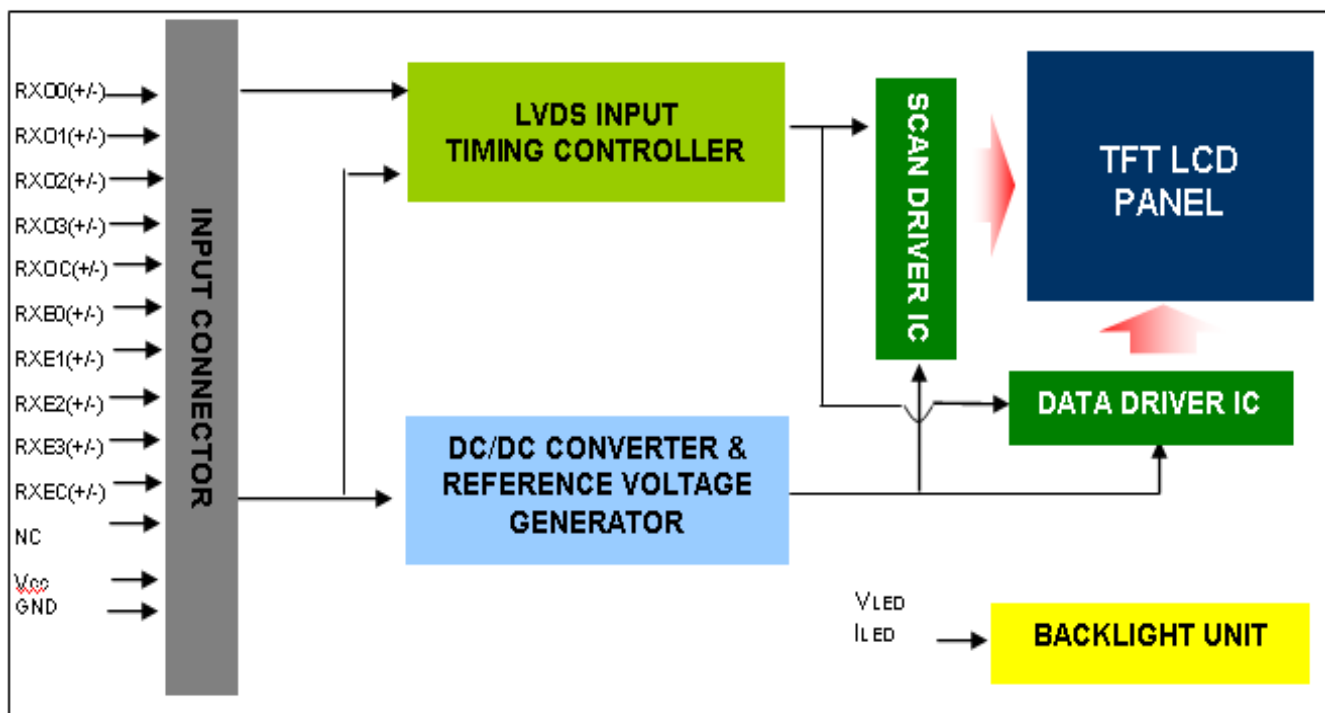


Fig. 4-1 Module Function Block Diagram

4.2. INTERFACE CONNECTIONS

4.2.1 Module LCD PIN ASSIGNMENT

Pin	Name	Description
1	RXO0-	Negative LVDS differential data input. Channel O0 (odd)
2	RXO0+	Positive LVDS differential data input. Channel O0 (odd)
3	RXO1-	Negative LVDS differential data input. Channel O1 (odd)
4	RXO1+	Positive LVDS differential data input. Channel O1 (odd)
5	RXO2-	Negative LVDS differential data input. Channel O2 (odd)
6	RXO2+	Positive LVDS differential data input. Channel O2 (odd)
7	GND	Ground
8	RXOC-	Negative LVDS differential clock input. (odd)
9	RXOC+	Positive LVDS differential clock input. (odd)
10	RXO3-	Negative LVDS differential data input. Channel O3(odd)
11	RXO3+	Positive LVDS differential data input. Channel O3 (odd)
12	RXE0-	Negative LVDS differential data input. Channel E0 (even)
13	RXE0+	Positive LVDS differential data input. Channel E0 (even)
14	GND	Ground
15	RXE1-	Negative LVDS differential data input. Channel E1 (even)
16	RXE1+	Positive LVDS differential data input. Channel E1 (even)
17	GND	Ground
18	RXE2-	Negative LVDS differential data input. Channel E2 (even)
19	RXE2+	Positive LVDS differential data input. Channel E2 (even)
20	RXEC-	Negative LVDS differential clock input. (even)
21	RXEC+	Positive LVDS differential clock input. (even)
22	RXE3-	Negative LVDS differential data input. Channel E3 (even)
23	RXE3+	Positive LVDS differential data input. Channel E3 (even)

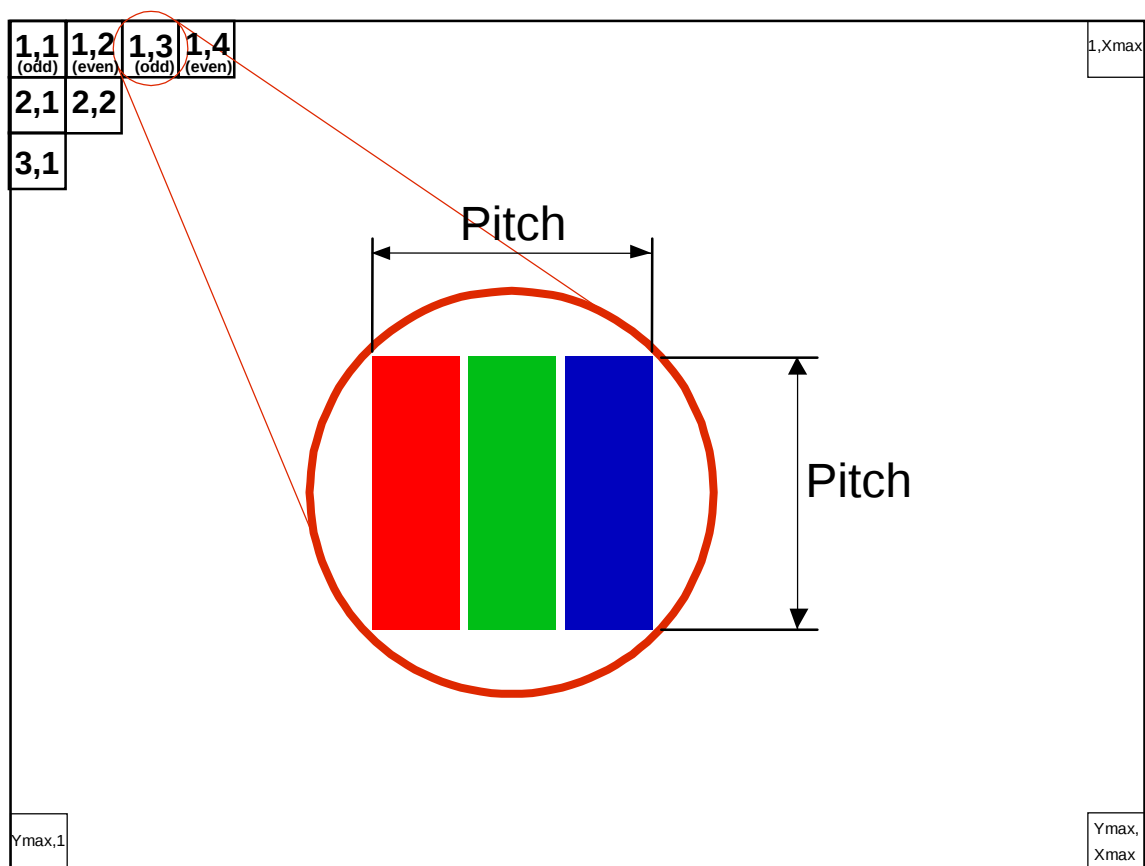
24	GND	Ground
25	NC	For LCD internal use only, Do not connect
26	NC	For LCD internal use only, Do not connect
27	NC	For LCD internal use only, Do not connect
28	Vcc	+5.0V power supply
29	Vcc	+5.0V power supply
30	Vcc	+5.0V power supply

4.2.2 Module Panel Connector Information

Item	Description
Manufacturer	P-TWO
Type part number	P-TWO:187098-30091
Mating housing part number	FI-X30H(JAE)

Note (1) The first pixel is odd

Note (2) Input signal of even and odd clock should be the same timing.



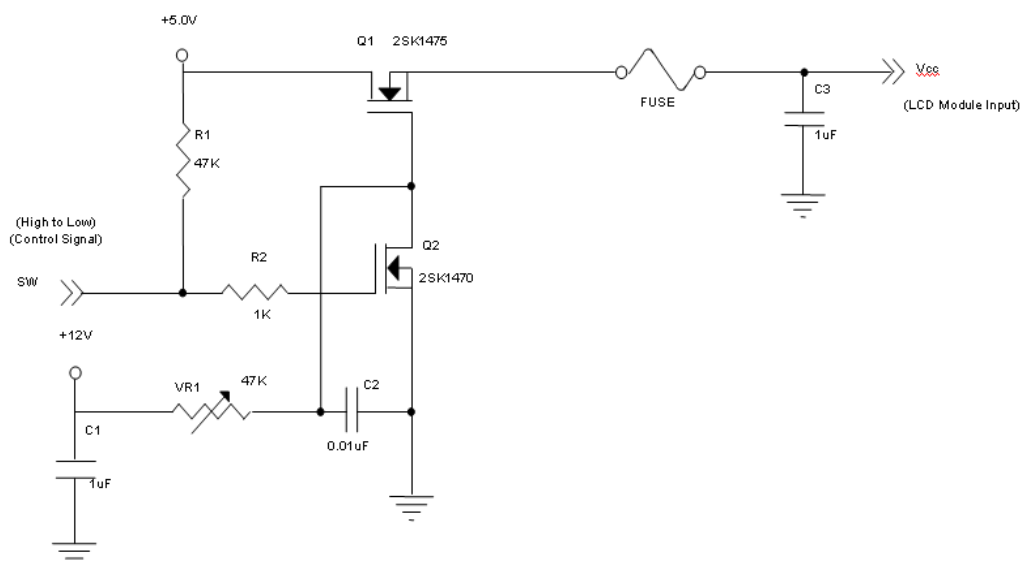
4.3 ELECTRICAL CHARACTERISTICS

4.3.1 LCD ELETRONICS SPECIFICATION

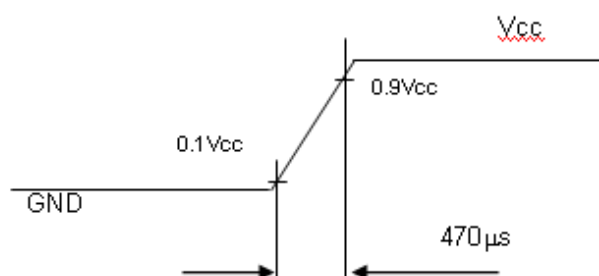
Parameter		Symbol	Value			Unit	Note
			Min.	Typ.	Max.		
Power Supply Voltage		V _{CC}	4.5	5.0	5.5	V	-
Ripple Voltage		V _{RP}	-	-	300	mV	-
Rush Current		I _{RUSH}	-	-	(3)	A	(2)
Power Supply Current	White	-	-	(TBD)	(TBD)	A	(3)a
	Black	-	-	(TBD)	(TBD)	A	(3)b
	Vertical Stripe	-	-	(TBD)	(TBD)	A	(3)c
Power Consumption		PLCD	-	(TBD)	(TBD)	Watt	(4)
LVDS interface	Differential Input Voltage	V _{ID}	100	-	600	mV	
	Common Input Voltage	V _{CM}	1.0	1.2	1.4	V	
	Differential Input High Threshold Voltage	V _{TH}	-	-	+100	mV	
	Differential Input Low Threshold Voltage	V _{TL}	-100	-	-	mV	

Note (1) The ambient temperature is Ta = 25 ± 2 °C.

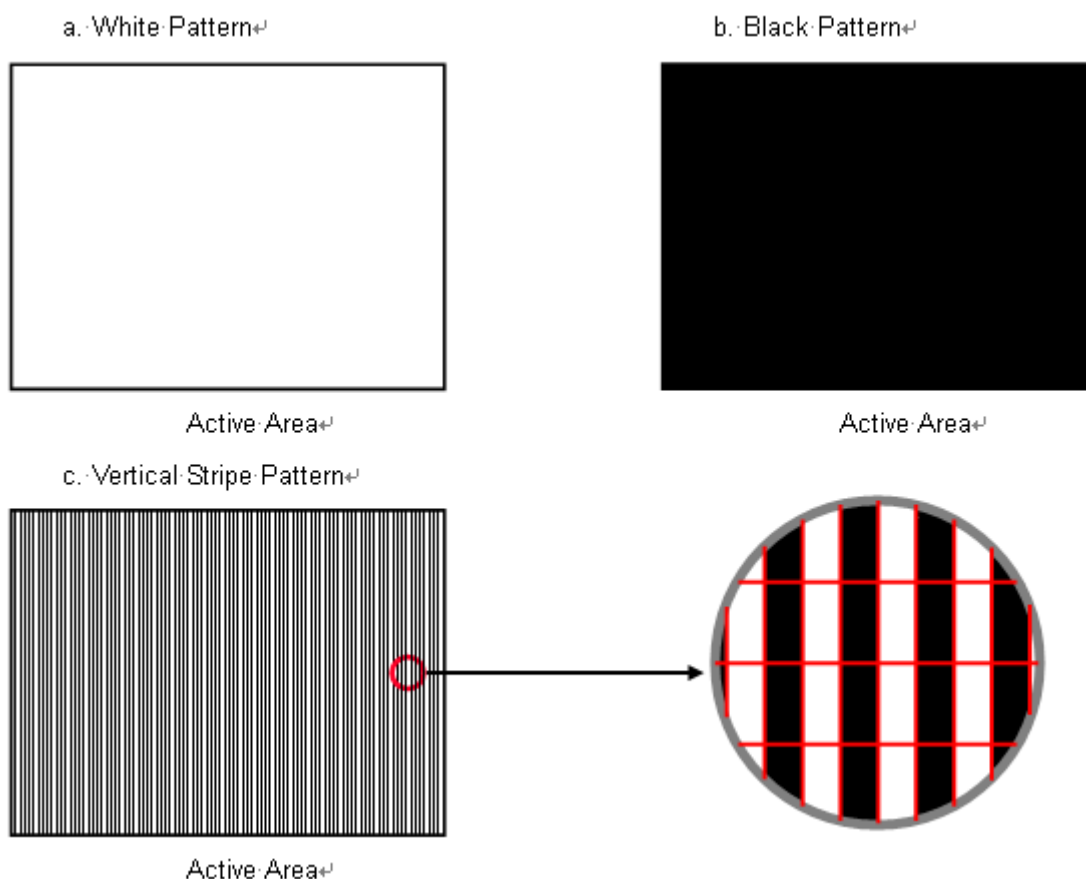
Note (2) Measurement Conditions:



Vcc rising time is 470μs



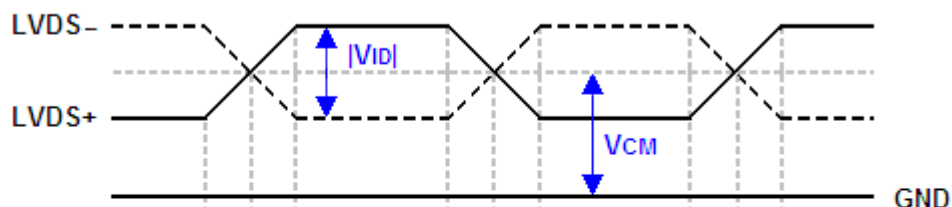
Note (3) The specified power supply current is under the conditions at $V_{CC} = 5.0\text{ V}$, $T_a = 25 \pm 2\text{ }^{\circ}\text{C}$, $F_r = 60\text{ Hz}$, whereas a power dissipation check pattern below is displayed.



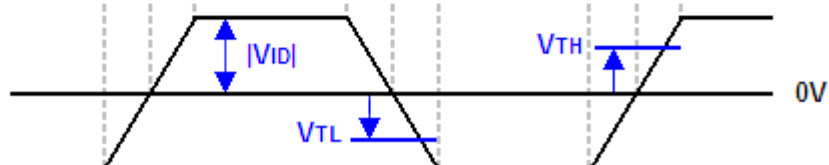
Note (4) The power consumption is specified at the pattern with the maximum current.

Note (5) The LVDS input characteristics are as follows:

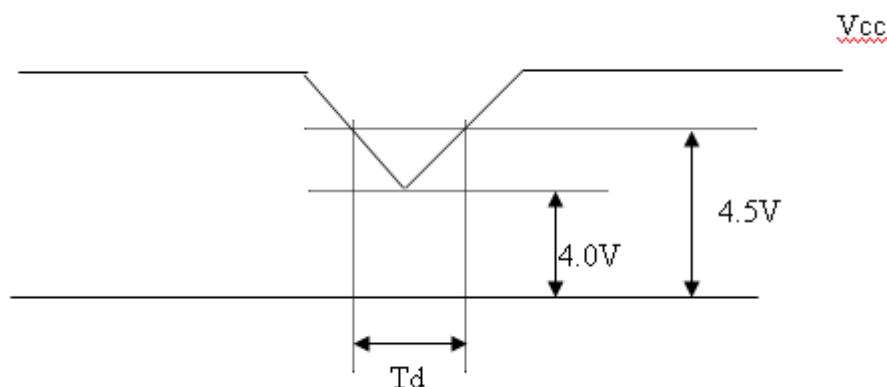
Single-end Signals



Differential Signal



4.3.2 Vcc Power Dip Condition



Dip condition: $4.0 \leq V_{cc} \leq 4.5$, $T_d \leq 20\text{ms}$

4.3.3 BACKLIGHT UNIT

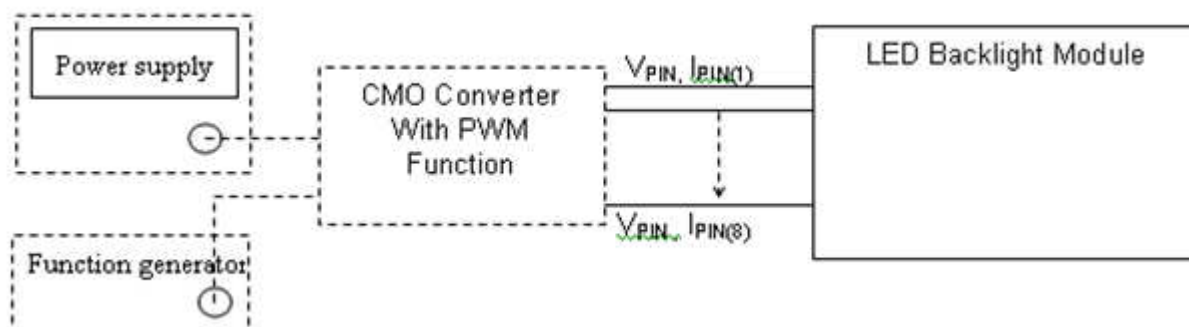
Parameter	Symbol	Value			Unit	Note
		Min.	Typ.	Max.		
LED Light Bar Input Voltage Per Input Pin	VPIN		31.0	35.0	V	(1), Duty=100%, IPIN=95mA
LED Light Bar Current Per Input Pin	IPIN		95	110	mA	(1), (2) Duty=100%
LED Life Time	LLED	40000			Hrs	(3)
Power Consumption	PBL	---	11.78	13.30	W	(1) Duty=100%, IPIN=95mA

Note (1) LED light bar input voltage and current are measured by utilizing a true RMS multimeter as shown below:

Note (2) $PBL(Typ) = IPIN(Typ) \times VPIN(Typ) \times (4)$ $PBL(Max) = IPIN(Typ) \times VPIN(Max) \times (4)$ input pins ,

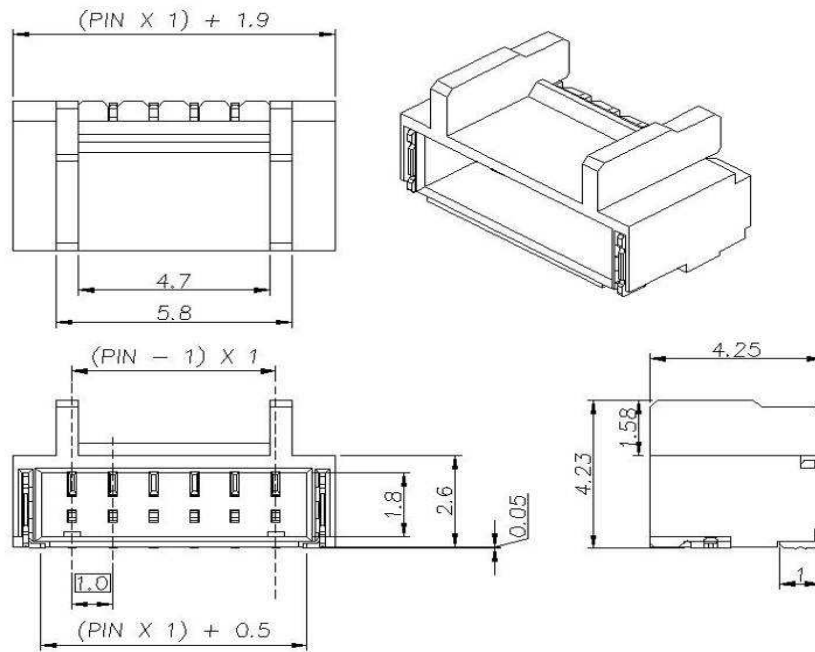
Note (3) The lifetime of LED is defined as the time when LED packages continue to operate under the conditions at $T_a = 25 \pm 2^\circ\text{C}$ and $I = (95)\text{mA}$ (per chip) until the brightness becomes $\leq 50\%$ of its original value.

Note (4) The module must be operated with constant driving current.



4.3.4 LIGHTBAR Connector Pin Assignment

(1) Connector Information:



Pin number	Description
1	LED1 negative polarity
2	LED2 negative polarity
3	Input voltage Power Supply
4	Input voltage Power Supply
5	LED3 negative polarity
6	LED4 negative polarity

Note (1) User's Mating Connector Part No.:

Connector (wire type): FCN(WM13-406-063N) or CviLux(CI1406M1HRK-NH) or equivalent.

4.4 LVDS INPUT SIGNAL SPECIFICATIONS

4.4.1 LVDS DATA MAPPING TABLE

LVDS Channel O0	LVDS output	D7	D6	D4	D3	D2	D1	D0
	Data order	OG0	OR5	OR4	OR3	OR2	OR1	OR0
LVDS Channel O1	LVDS output	D18	D15	D14	D13	D12	D9	D8
	Data order	OB1	OB0	OG5	OG4	OG3	OG2	OG1
LVDS Channel O2	LVDS output	D26	D25	D24	D22	D21	D20	D19
	Data order	DE	NA	NA	OB5	OB4	OB3	OB2
LVDS Channel O3	LVDS output	D23	D17	D16	D11	D10	D5	D27
	Data order	NA	OB7	OB6	OG7	OG6	OR7	OR6
LVDS Channel E0	LVDS output	D7	D6	D4	D3	D2	D1	D0
	Data order	EG0	ER5	ER4	ER3	ER2	ER1	ER0
LVDS Channel E1	LVDS output	D18	D15	D14	D13	D12	D9	D8
	Data order	EB1	EB0	EG5	EG4	EG3	EG2	EG1
LVDS Channel E2	LVDS output	D26	D25	D24	D22	D21	D20	D19
	Data order	DE	NA	NA	EB5	EB4	EB3	EB2
LVDS Channel E3	LVDS output	D23	D17	D16	D11	D10	D5	D27
	Data order	NA	EB7	EB6	EG7	EG6	ER7	ER6

4.4.2 COLOR DATA INPUT ASSIGNMENT

The brightness of each primary color (red, green and blue) is based on the 8-bit gray scale data input for the color. The higher the binary input, the brighter the color. The table below provides the assignment of color versus data input.

Color		Data Signal																							
		Red								Green								Blue							
		R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0
Basic Colors	Black	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	Blue	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Cyan	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Magenta	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Yellow	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	White	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
Gray Scale Of Red	Red(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(1)	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(2)	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
	Red(253)	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(254)	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(255)	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Gray Scale Of Green	Green(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0
	Green(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
	Green(253)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0
	Green(254)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0
	Green(255)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
Gray Scale Of Blue	Blue(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Blue(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
	Blue(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
	Blue(253)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1
	Blue(254)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0
	Blue(255)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1

Note (1) 0: Low Level Voltage, 1: High Level Voltage

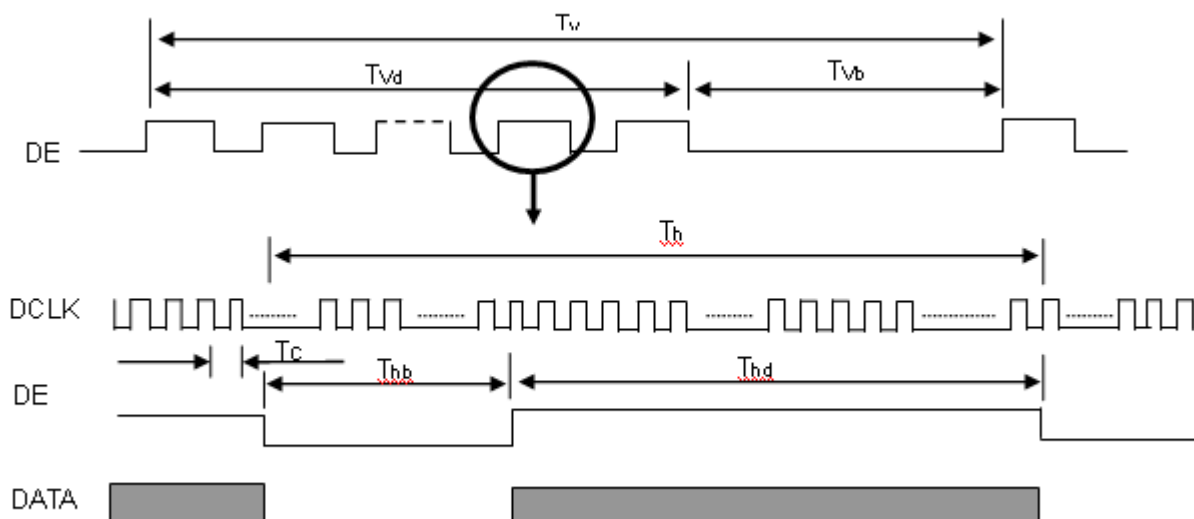
4.5 DISPLAY TIMING SPECIFICATIONS

The input signal timing specifications are shown as the following table and timing diagram.

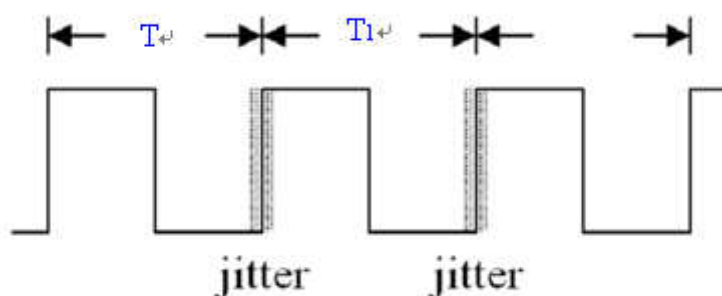
Signal	Item	Symbol	Min.	Typ.	Max.	Unit	Note
LVDS Clock	Frequency	F _c	58.54	74.25	97.98	MHz	-
	Period	T _c	-	13.47		ns	
	Input cycle to cycle jitter	T _{rcj}	-0.02*TC	-	0.02*TC	ns	(1)
	Input Clock to data skew	TLVCC S	-0.02*TC		0.02*TC		(2)
	Spread spectrum modulation range	F _{ckin_mod}	0.97*FC	-	1.03*FC	MHz	(3)
	Spread spectrum modulation frequency	F _{SSM}	-	-	100	KHz	
Vertical Display Term	Frame Rate	Fr	50	60	75	Hz	
	Total	T _v	1115	1125	1136	Th	T _v =T _{vd} +T _{vb}
	Active Display	T _{vd}	1080	1080	1080	Th	-
	Blank	T _{vb}	T _v -T _{vd}	T _v -T _{vd}	T _v -T _{vd}	Th	-
Horizontal Display Term	Total	T _h	1050	1100	1150	Tc	T _h =T _{hd} +T _{hb}
	Active Display	T _{hd}	960	960	960	Tc	-
	Blank	T _{hb}	T _h -T _{hd}	T _h -T _{hd}	T _h -T _{hd}	Tc	-

Note: Because this module is operated by DE only mode, Hsync and Vsync input signals are ignored.

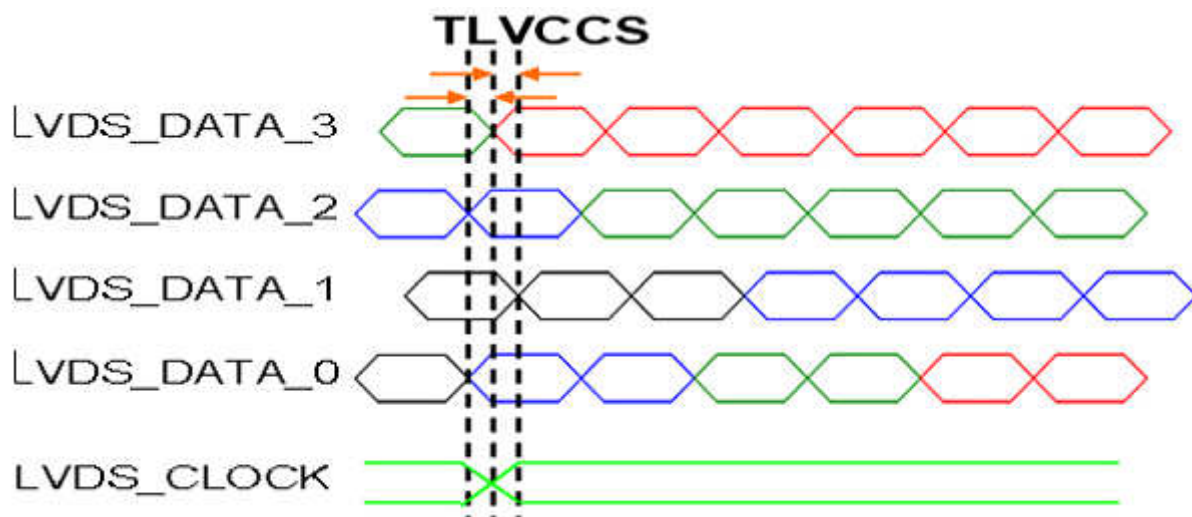
INPUT SIGNAL TIMING DIAGRAM



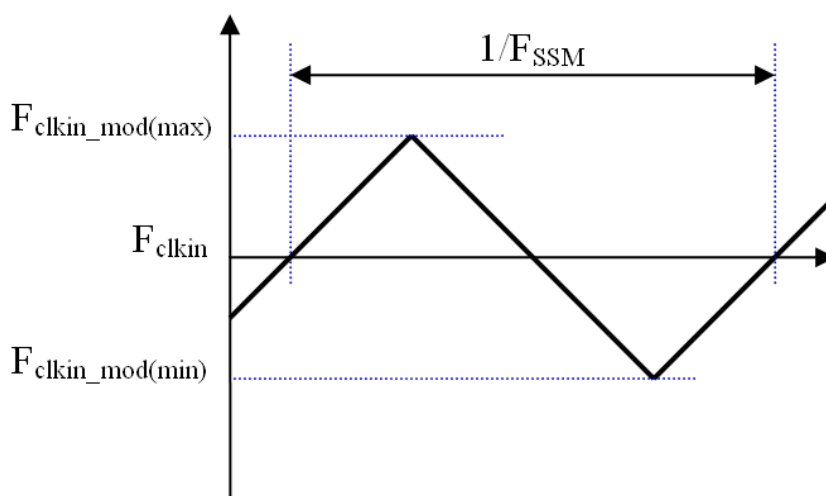
Note (1) The input clock cycle-to-cycle jitter is defined as below figures. $Trcl = |T_1 - T_1|$



Note (2) Input Clock to data skew is defined as below figures.



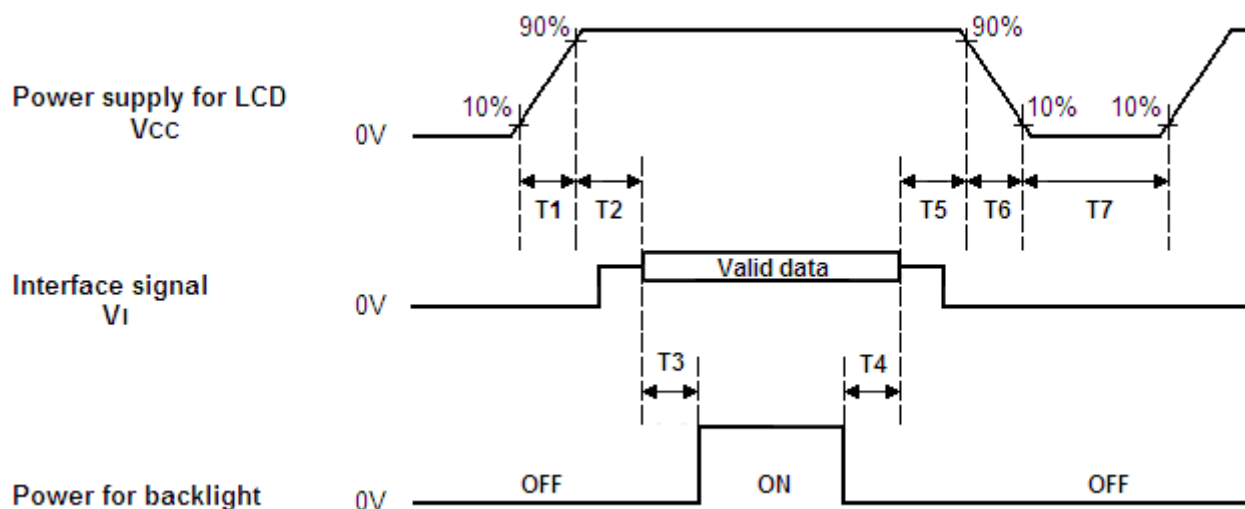
Note (3) The SSCG (Spread spectrum clock generator) is defined as below figures.



Note(4) The DCLK range at last line of V-blank should be set in 0 to Hdisplay/2

4.6 POWER ON/OFF SEQUENCE

The power sequence specifications are shown as the following table and diagram.



Timing Specifications:

Parameters	Values			Units
	Min	Typ.	Max	
T1	0.5	--	10	ms
T2	0	30	50	ms
T3	450	--	--	ms
T4	100	250	--	ms
T5	0	20	50	ms
T6	0.1	--	100	ms
T7	1000	--	--	ms

Note (1) The supply voltage of the external system for the module input should be the same as the definition of Vcc.

Note (2) When the backlight turns on before the LCD operation of the LCD turns off, the display may momentarily become abnormal screen.

Note (3) In case of VCC = off level, please keep the level of input signals on the low or keep a high impedance.

Note (4) T7 should be measured after the module has been fully discharged between power off and on period.

Note (5) Interface signal shall not be kept at high impedance when the power is on.

Note (6) INX won't take any responsibility for the products which are damaged by the customers not following the Power Sequence.

Note (7) There might be slight electronic noise when LCD is turned off (even backlight unit is also off). To avoid this symptom, we suggest "Vcc falling timing" to follow "t6 spec".

5. OPTICAL CHARACTERISTICS

5.1 TEST CONDITIONS

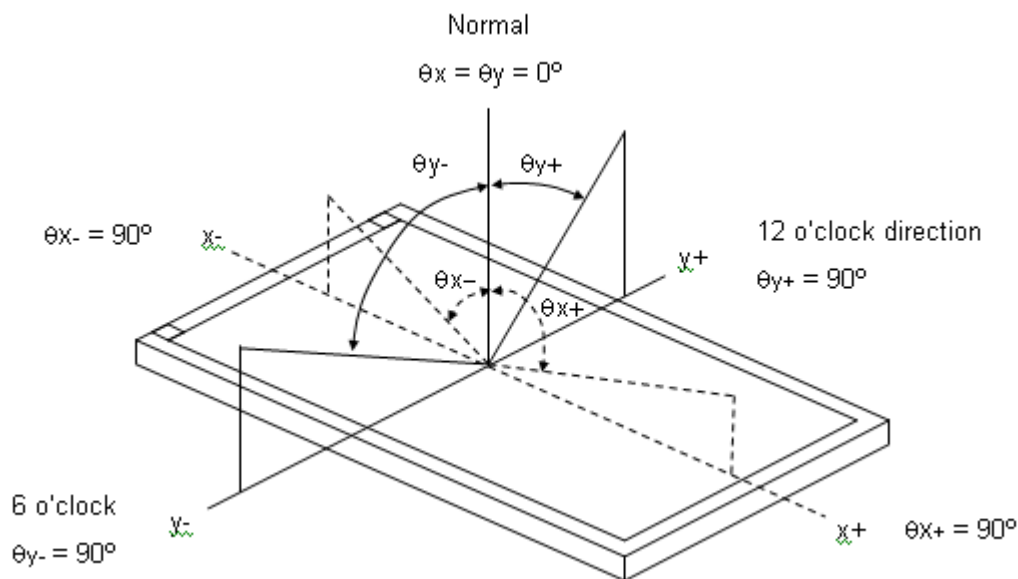
Item	Symbol	Value	Unit
Ambient Temperature	Ta	25 ± 2	°C
Ambient Humidity	Ha	50 ± 10	%RH
Supply Voltage	V _{CC}	5	V
Input Signal	According to typical value in "3. ELECTRICAL CHARACTERISTICS"		
LED Light Bar Input Current Per Input Pin	I _{PIN}	95	mA _{DC}
PWM Duty Ratio	D	100	%
LED Light Bar Test Converter	INX R373B0000U000		

5.2 OPTICAL SPECIFICATIONS

The relative measurement methods of optical characteristics are shown in 5.2. The following items should be measured under the test conditions described in 5.1 and stable environment shown in Note (5).

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Color Chromaticity (CIE 1931)	Red	Rx		Typ – 0.03	0.633	Typ + 0.03	-	(1), (5)
		Ry			0.340			
	Green	Gx			0.314			
		Gy			0.632			
	Blue	Bx			0.159			
		By			0.060			
	White	Wx			0.313			
		Wy			0.329			
	Center Luminance of White (Center of Screen)				L _C			
Contrast Ratio		CR	2000	3000			(2), (5)	
Response Time	Gray to Gray	T _{GIG_AVE}	θ _x =0°, θ _y =0°	-	20	30	ms	(3)
White Variation		W		72	75	-	-	(5), (6)
Viewing Angle	Horizontal	θ _{x-} + θ _{x+}	CR ≥ 10	160	178	---	Deg.	(1), (5)
	Vertical	θ _{y-} + θ _{y+}		160	178	---		

Note (1) Definition of Viewing Angle (θ_x , θ_y):



Note (2) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

$$\text{Contrast Ratio (CR)} = L_{255} / L_0$$

L255: Luminance of gray level 255

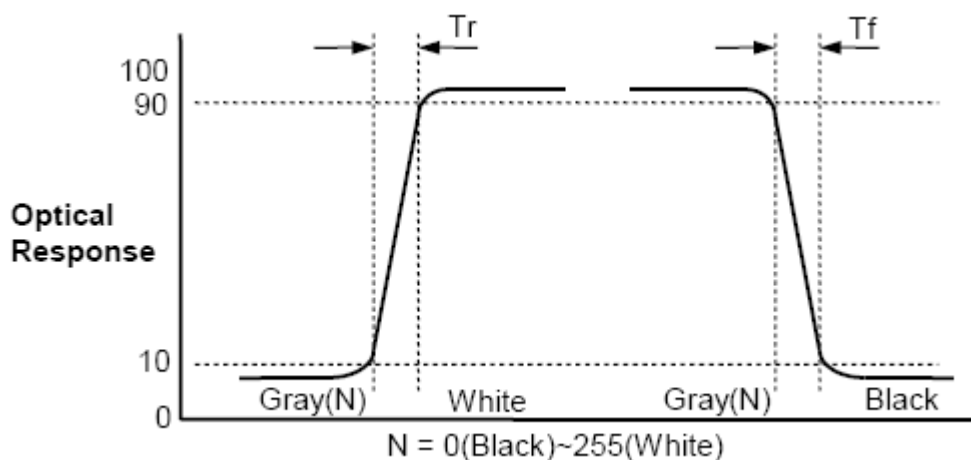
L 0: Luminance of gray level 0

$$\text{CR} = \text{CR} (5)$$

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note (6).

Note (3) Definition of Gray to Gray Response Time :

G to G(BW) Response time is defined as the following figure and shall be measured by switching the input signal for "Gray(N)" and "Black or White".



The Gray to Gray response time is defined as the following figure and shall be measured by switching the input signal for "Gray To Gray".

- $T_{\text{GTG_AVE}}$ is the total average time at rising time and falling time for "Gray To Gray".
- If system use ODC (Over Driving Circuit) function, $T_{\text{GTG_AVE}}$ may be 5ms~10ms.
- * It depends on Overshoot rate.

Gray to Gray		Rising time								
		0	31	63	95	127	159	191	223	255
Falling time	0									
	31									
	63									
	95									
	127									
	159									
	191									
	223									
	255									

Note (4) Definition of Luminance of White (L_c):

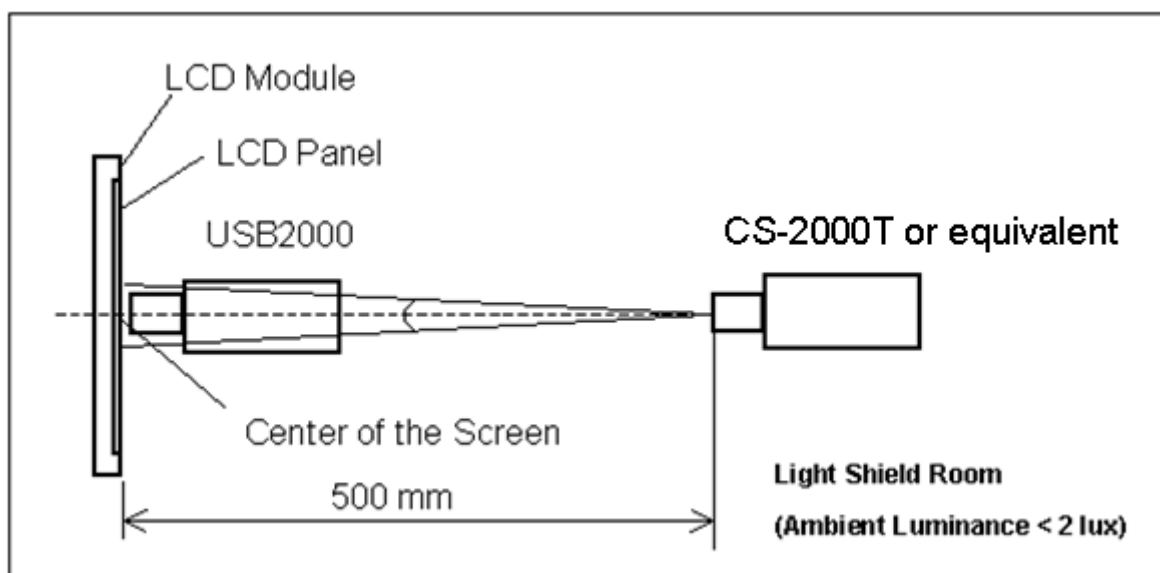
Measure the luminance of gray level 255 at center point

$$L_c = L(5)$$

$L(x)$ is corresponding to the luminance of the point X at Figure in Note (6).

Note (5) Measurement Setup:

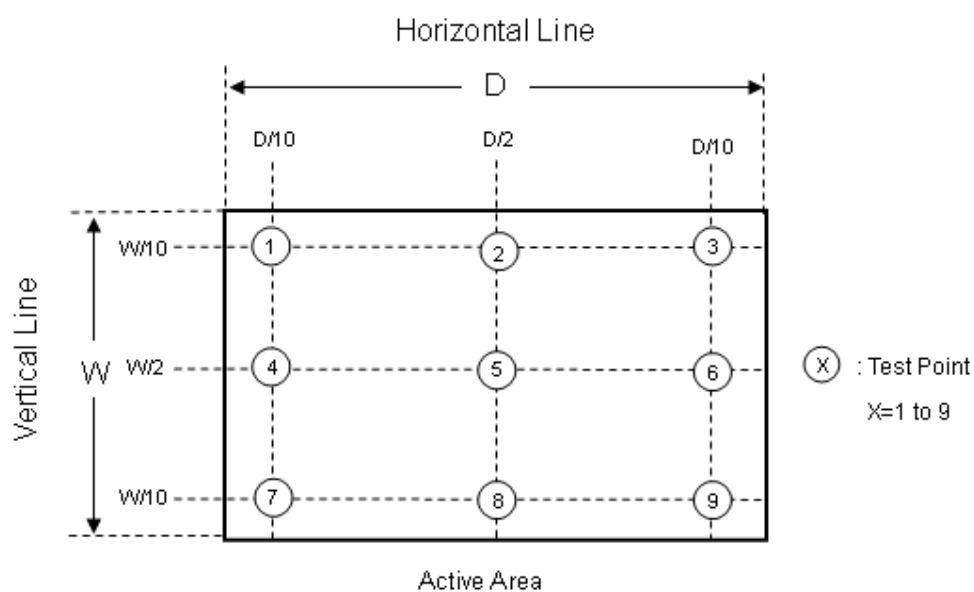
The LCD module should be stabilized at given temperature for 40 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 40 minutes in a windless room.



Note (6) Definition of White Variation (δW):

Measure the luminance of gray level 255 at 9 points

$$\delta W = (\text{Minimum } [L(1) \sim L(9)] / \text{Maximum } [L(1) \sim L(9)]) * 100\%$$



6. RELIABILITY TEST ITEM

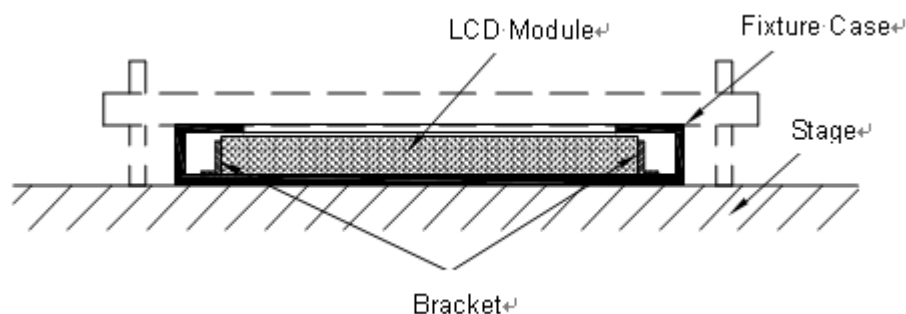
Items	Required Condition	Note
Temperature Humidity Bias (THB)	Ta= 50℃ , 80%RH, 240hours	
High Temperature Operation (HTO)	Ta= 50℃ , 240hours	
Low Temperature Operation (LTO)	Ta= 0℃ , 240hours	
High Temperature Storage (HTS)	Ta= 60℃ , 240hours	
Low Temperature Storage (LTS)	Ta= -20℃ , 240hours	
Vibration Test (Non-operation)	Acceleration: 1.5 G Wave: Sine Frequency: 10 - 300 Hz Sweep: 30 Minutes each Axis (X, Y, Z)	
Shock Test (Non-operation)	Acceleration: 50 G Wave: Half-sine Active Time: 11 ms Direction : ± X, ± Y, ± Z.(one time for each Axis)	
Thermal Shock Test (TST)	-20℃/30min , 60℃ / 30min , 100 cycles	
On/Off Test	25℃ ,On/10sec , Off /10sec , 30,000 cycles	
ESD (Electro Static Discharge)	Contact Discharge: ± 8KV, 150pF(330Ω)	
	Air Discharge: ± 15KV, 150pF(330Ω)	
Altitude Test	Operation:10,000 ft / 24hours Non-Operation:30,000 ft / 24hours	

Note (1) criteria : Normal display image with no obvious non-uniformity and no line defect.

Note (2) Evaluation should be tested after storage at room temperature for more than two hour

Note (3) At testing Vibration and Shock, the fixture in holding the module has to be hard and rigid enough so that the module would not be twisted or bent by the fixture.

The fixing condition is shown as below:



7. PACKING

7.1 PACKING SPECIFICATIONS

- (1) LCD 11 modules / 1 Box
- (2) Box dimensions: 620(L) X 348(W) X 430(H) mm
- (3) Weight: approximately: 33kg (11modules per box)

7.2 PACKING METHOD

- (1) Carton Packing should have no failure in the following reliability test items.

Test Item	Test Conditions	Note
Vibration	ISTA STANDARD Random, Frequency Range: 1 – 200 Hz Top & Bottom: 30 minutes (+Z), 10 min (-Z), Right & Left: 10 minutes (X) Back & Forth 10 minutes (Y)	Non Operation
Dropping Test	1 Corner , 3 Edge, 6 Face,(31)cm	Non Operation

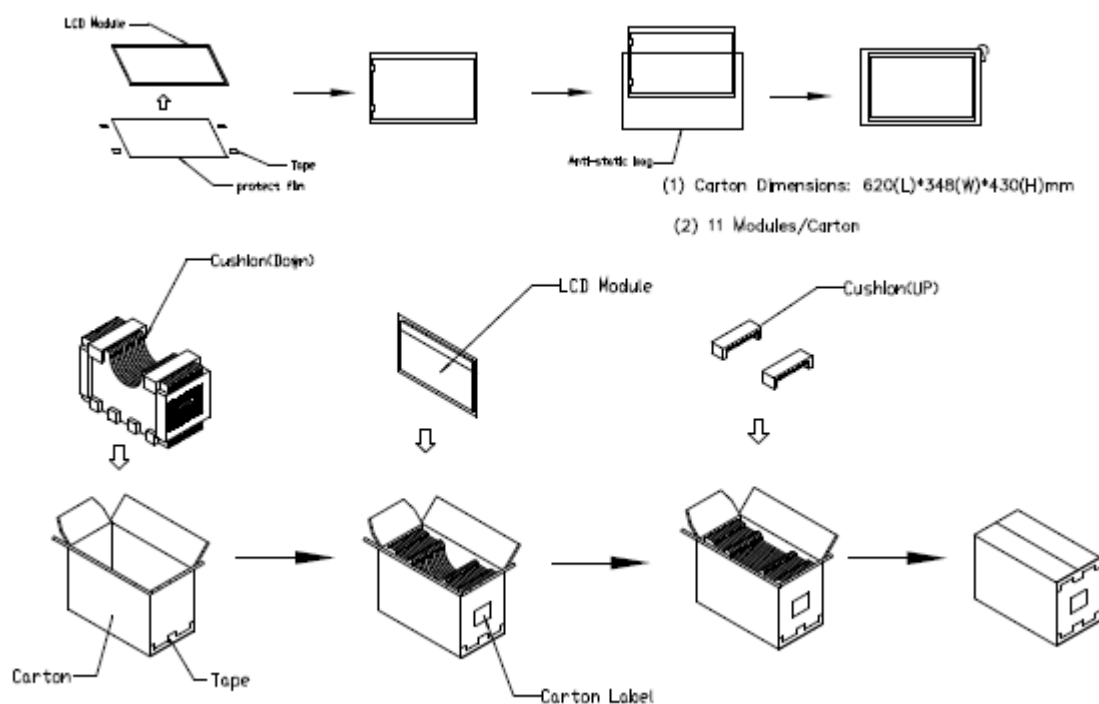


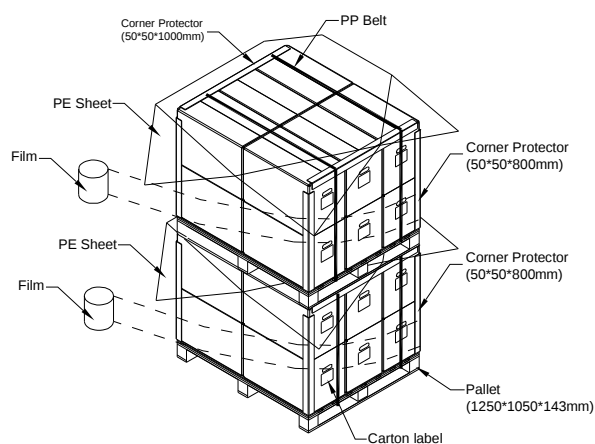
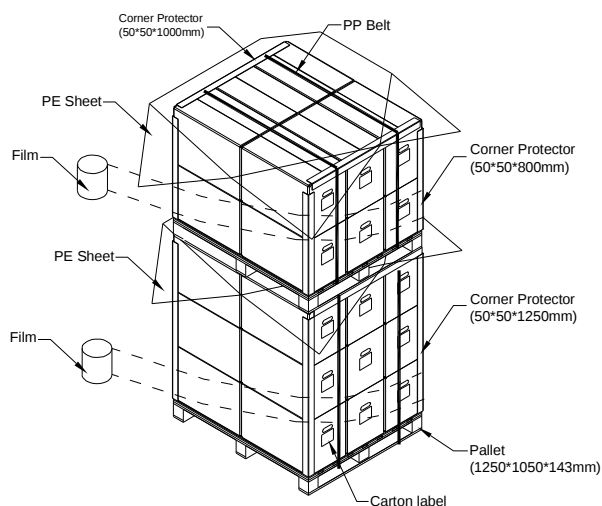
Figure. 7-1 Packing method

7.3 PALLET

For ocean shipping

Sea / Land Transportation (40ft HQ Container)

Sea / Land Transportation (40ft Container)



For air transport

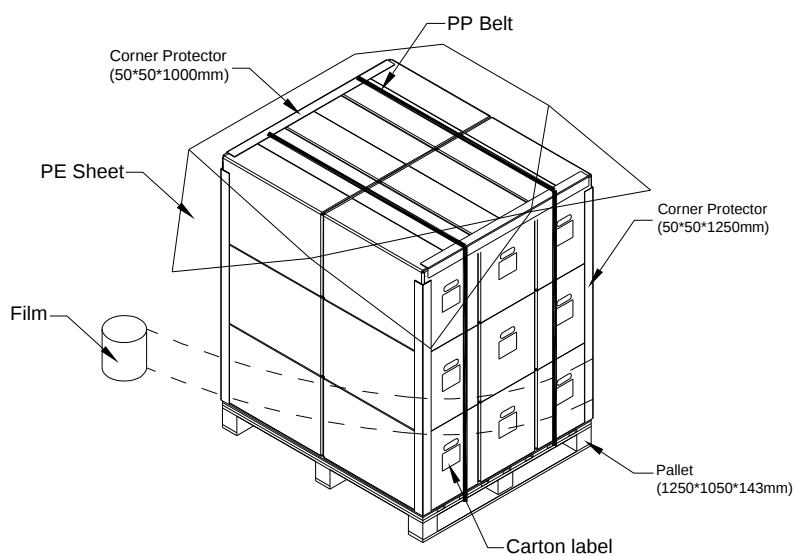
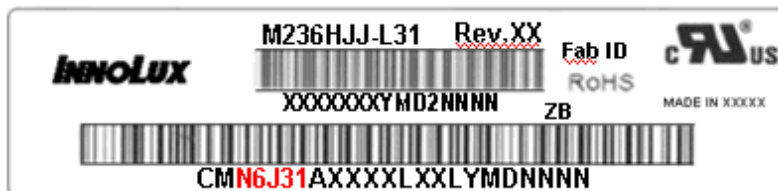


Figure. 7-2 Packing method

8. INX MODULE LABEL

The barcode nameplate is pasted on each module as illustration, and its definitions are as following explanation.



(a) Model Name: M236HJJ-L31

(b) Revision: Rev. XX, for example: A0, A1... B1, B2... or C1, C2...etc.

(c) INX barcode definition:

Serial ID: XX-XX-X-XX-YMD-L-NNNN

Code	Meaning	Description
XX	INX internal use	-
XX	Revision	Cover all the change
X	INX internal use	-
XX	INX internal use	-
YMD	Year, month, day	Year: 0~9, 2001=1, 2002=2, 2003=3...2010=0, 2011=1, 2012=2... Month: 1~12=1, 2, 3, ~, 9, A, B, C Day: 1~31=1, 2, 3, ~, 9, A, B, C, ~, W, X, Y, exclude I, O, and U.
L	Product line #	Line 1=1, Line 2=2, Line 3=3, ...
NNNN	Serial number	Manufacturing sequence of product

(d) Customer's barcode definition:

Serial ID: CM- N6J31-X-X-X-XX-L-XX-L-YMD-NNNN

Code	Meaning	Description
CM	Supplier code	INX=CM
N6J31	Model number	M236HJJ-L31
X	Revision code	Non ZBD: 1,2,~,8,9 / ZBD: A~Z
X	Source driver IC code	Century=1, CLL=2, Demos=3, Epson=4, Fujitsu=5, Himax=6, Hitachi=7, Hynix=8, LDI=9, Matsushita=A, NEC=B, Novatek=C, OKI=D, Philips=E, Renasas=F, Samsung=G, Sanyo=H, Sharp=I, TI=J, Topro=K, Toshiba=L, Windbond=M, ILITEK=Q, Fiti=Y, None IC =Z
X	Gate driver IC code	
XX	Cell location	Tainan Taiwan=TN, Ningbo China=CN, Hsinchu Taiwan=SC
L	Cell line #	1,2,~,9,A,B,~,Y,Z
XX	Module location	Tainan, Taiwan=TN ; Ningbo China=NP ; Shenzhen China=SH ; Nanhai China=NH
L	Module line #	1,2,~,9,A,B,~,Y,Z
YMD	Year, month, day	Year: 0~9, 2001=1, 2002=2, 2003=3...2010=0, 2011=1, 2012=2... Month: 1~12=1, 2, 3, ~, 9, A, B, C Day: 1~31=1, 2, 3, ~, 9, A, B, C, ~, T, U, V
NNNN	Serial number	By LCD supplier

(e) FAB ID(UL Factory ID):

Region	Factory ID
TWINX	GEMN
NBCMI	LEOO
NBCMI	VIRO
NBCME	CANO
NHCM1	CAPG

9. PRECAUTIONS

9.1 ASSEMBLY AND HANDLING PRECAUTIONS

- (1) Do not apply rough force such as bending or twisting to the module during assembly.
- (2) To assemble or install module into user's system can be only in clean working areas. The dust and oil may cause electrical short or worsen the polarizer.
- (3) It's not permitted to have pressure or impulse on the module because the LCD panel and Backlight will be damaged.
- (4) Always follow the correct power sequence when LCD module is connecting and operating. This can prevent damage to the CMOS LSI chips during latch-up.
- (5) Do not pull the I/F connector in or out while the module is operating.
- (6) Do not disassemble the module.
- (7) Use a soft dry cloth without chemicals for cleaning, because the surface of polarizer is very soft and easily scratched.
- (8) It is dangerous that moisture come into or contacted the LCD module, because moisture may damage LCD module when it is operating.
- (9) High temperature or humidity may reduce the performance of module. Please store LCD module within the specified storage conditions.
- (10) When ambient temperature is lower than 10°C may reduce the display quality. For example, the response time will become slowly.
- (11) Do not press or scratch the surface harder than a HB pencil lead on the panel because the polarizer is very soft and easily scratched.

9.2 STORAGE PRECAUTIONS

- (1) Do not leave the module in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0°C to 35°C and relative humidity of less than 70%
- (2) Do not store the TFT – LCD module in direct sunlight
- (3) The module should be stored in dark place. It is prohibited to apply sunlight or fluorescent light in storing

9.3 OPERATION PRECAUTIONS

- (1) The LCD product should be operated under normal condition.

Normal condition is defined as below :

Temperature : 20±15°C

Humidity: 65±20%

Display pattern : continually changing pattern(Not stationary)

- (2) If the product will be used in extreme conditions such as high temperature, high humidity, high altitude, display pattern or operation time etc... It is strongly recommended to contact INX for application engineering advice. Otherwise, its reliability and function may not be guaranteed.

9.4 SAFETY PRECAUTIONS

- (1) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, skin or clothes, it has to be washed away thoroughly with soap.
- (2) After the module's end of life, it is not harmful in case of normal operation and storage.

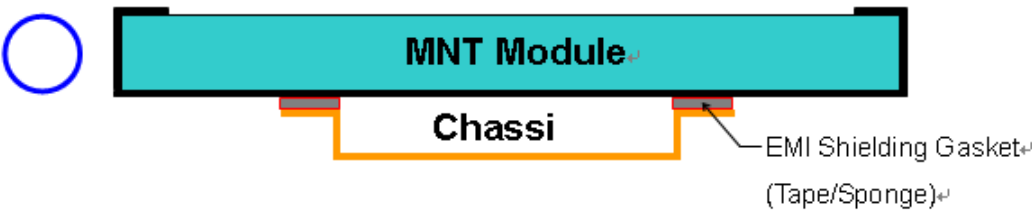
9.5 SAFETY STANDARDS

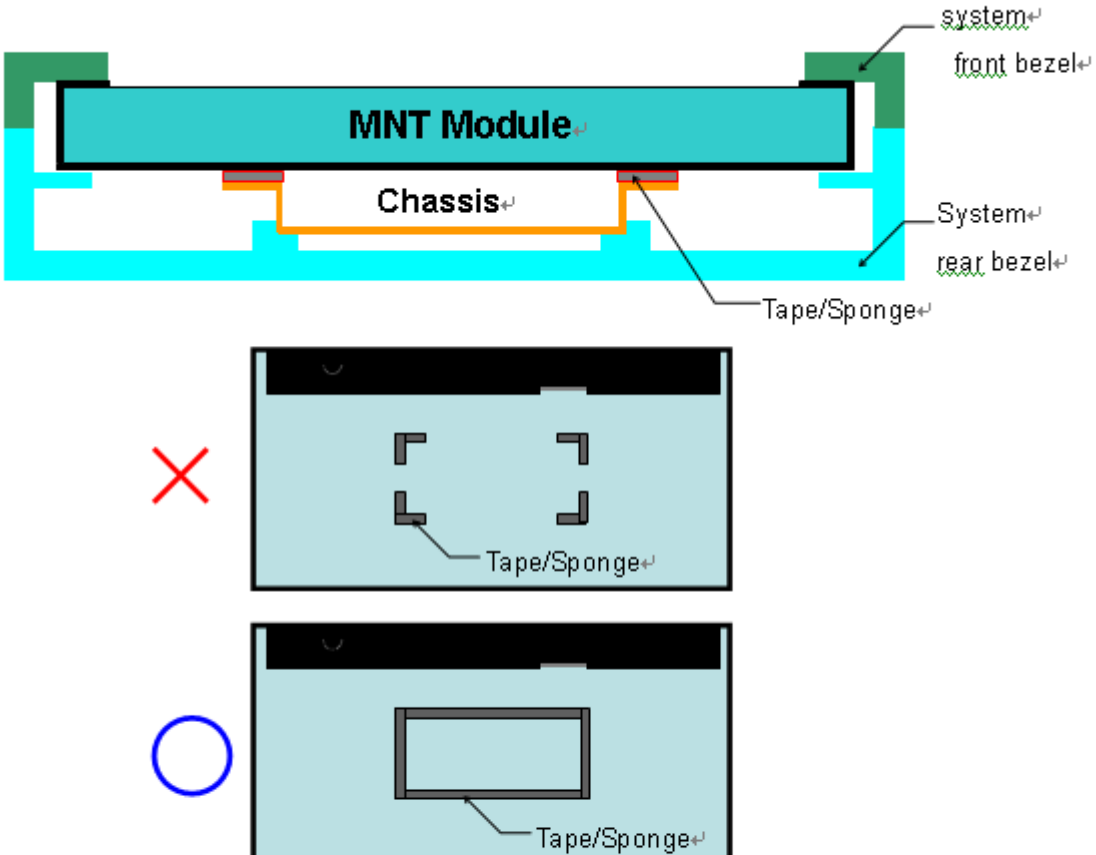
The LCD module should be certified with safety regulations as follows:

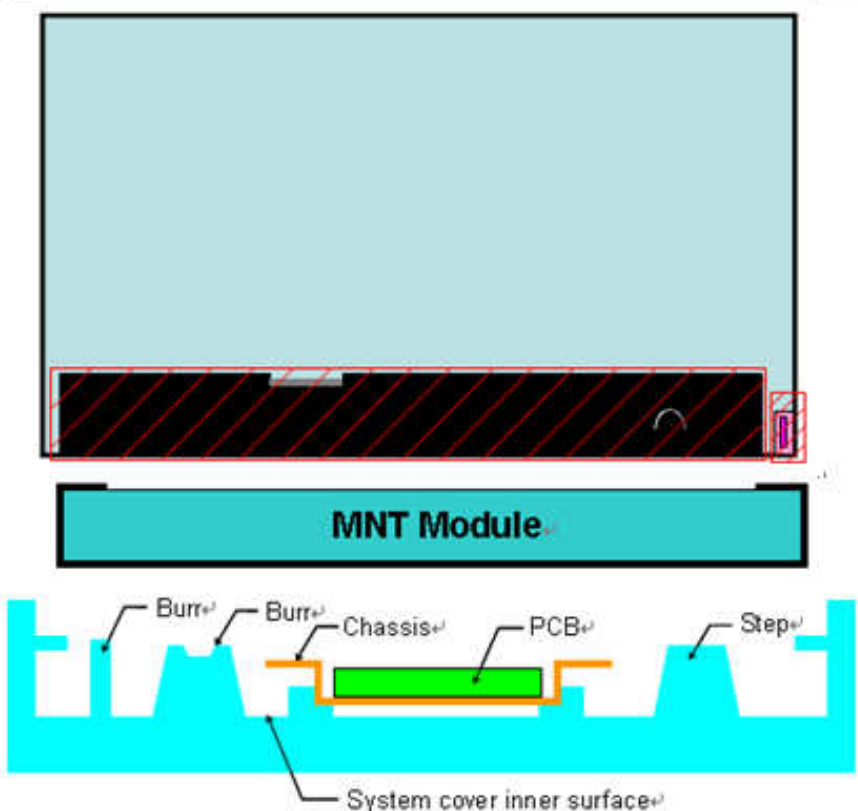
- (1) UL60950-1 or updated standard.
- (2) IEC60950-1 or updated standard.

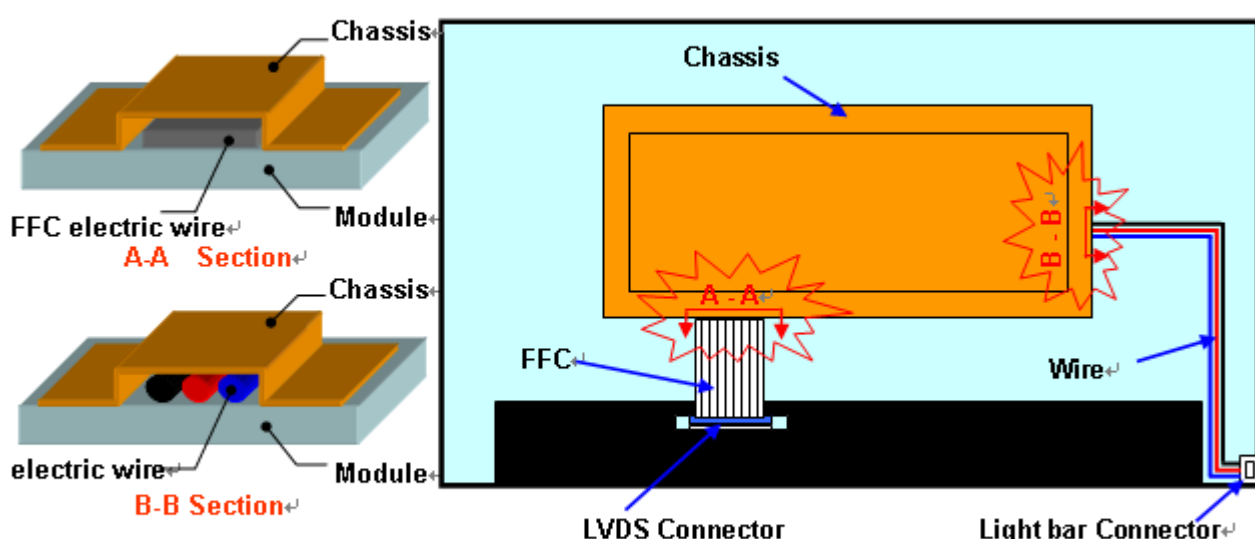
9.6 OTHER

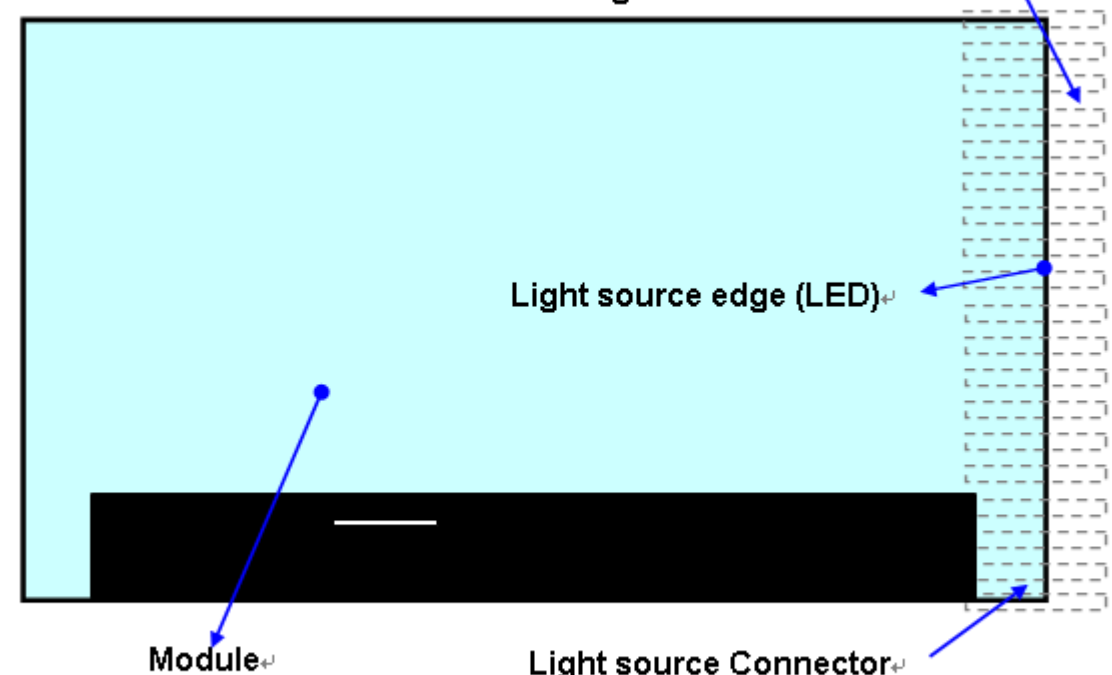
Appendix 1. SYSTEM COVER DESIGN NOTICE

1.	Set Chassis and MNT Module touching Mode
✗	 MNT Module Chassis spring
△	 MNT Module Chassis Flat sheetmetal
○	 MNT Module Chassi EMI Shielding Gasket (Tape/Sponge)
Definition	a) To prevent from abnormal display & white spot after Mechanical test, it is not recommended to used spring type chassis. b) We suggest the contact mode between Chassis and Module rear cover is Tape/Sponge, sencond is Flat sheetmetal type chassis (Don't interference from flat sheetmeter of chassis to rear cover of Module).

2	Tape/sponge design on system inner surface
	 The diagram illustrates the correct and incorrect placement of Tape/Sponge on the system inner surface. The top part shows a cross-section of the MNT Module, Chassis, and System with labels for front bezel, rear bezel, and Tape/Sponge. Below, two top-down views of the system inner surface are shown. The first view, marked with a red 'X', shows four small pieces of Tape/Sponge at the corners. The second view, marked with a blue circle, shows a single rectangular piece of Tape/Sponge covering the entire area between the chassis and the module rear cover.
Definition	a) To prevent from abnormal display & white spot after Mechanical test, We suggest using Tape/Sponge as medium between chassis and Module rear cover could reduce the occurrence of white spot. b) When using the Tape/Sponge, suggest it be lay over between set chassis and module rear cover. it is not recommended to add tape/sponge in separate location. Since each tape/sponge may act as pressure concentration location.

3	System inner surface examination
 The diagram illustrates the system inner surface examination. It shows a light blue rectangle representing the system cover. Below it is a black rectangle with red diagonal hatching, labeled 'MNT Module'. Below the hatched area is a cross-section diagram of the system cover inner surface. It shows a blue base with several features: 'Burr' (sharp edges), 'Chassis' (orange outline), 'PCB' (green rectangle), and 'Step' (a change in height). A red hatched area is also shown on the PCB. A label 'System cover inner surface' points to the blue base. A label '禁佈區' (Prohibited Area) points to the red hatched area on the PCB.	
Definition	a). Burr at logo edge, step, protrusion or PCB board will easily cause white spot. b). Keeping flat surface underneath module is recommended. c). The area () on Module PCBA and Light bar connector should keep at least 1mm gap to any structure with System cover inner surface.

4	The overlapping part on System's Chassis and electric wire needs gap structure.
 The diagram illustrates the required gap structure for the overlapping part of the System's Chassis and electric wire. It includes two cross-sections: A-A Section showing the FFC electric wire and B-B Section showing the electric wire. The top-down view shows the Chassis, FFC, Wire, LVDS Connector, and Light bar Connector. Red jagged lines indicate the gap structure needed to avoid white spots.	
Definition	The overlapping part on System's Chassis and electric wire (FPC、FFC and wire) needs gap structure to avoid display of white spot by pressing overlapping part cause interference.

5	System cover's ventilation outlet structure
Set ventilation outlet structure on Light source side of module.  The diagram shows the ventilation outlet structure on the light source side of the module. It includes labels for the Module, Light source edge (LED), and Light source Connector. A dashed line indicates the ventilation outlet structure on the side of the Module Light bar in the system cover inner surface.	
Definition	To prevent from abnormal display of light leakage, We suggest to set ventilation outlet structure on side of Module Light bar in system cover inner surface.

Appendix 2. OUTLINE DRAWING